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**(54) METHOD OF CONNECTION OF ELECTRONIC PARTS BY SOLDERING**

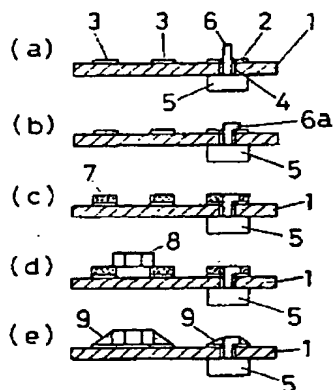
**(57) Abstract:**

**PURPOSE:** To make highly flexible the design, parts selection, and structure selection, keeping high productivity and high mounting density by mounting surface-mounting type electronic parts and insertion type electronic parts on the same wiring board, printing and supplying solder paste simultaneously through the same printing plate, and simultaneously performing reflow soldering.

**CONSTITUTION:** A lead wire 6 of insertion type electronic parts 5 is inserted into a lead wire insertion hole 4 in a printed board 1, and a portion of the tip end of the lead wire 6 protruding from a wiring board 1 surface is folded at a right angle so as to be parallel to the wiring board surface to provide a folded portion 6a. Then, solder paste 7 is printed on the lead wire tip end folded portion 6a and on a soldering land 6 for the surface mounting type electronic parts, simultaneously, and in succession the surface mounting type electronic parts 8 is mounted on the soldering paste 7 printed on the surface-mounting type electronic parts soldering land. Finally, the whole sample is held in an infrared furnace and a hot wind furnace, etc., to reflow the

solder for yielding a soldered portion 9. Hereby, there are realized simultaneous printing of the soldering paste and simultaneous soldering by the reflow soldering.

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